

## 85V N-Channel Enhancement Mode Power MOSFET

## Description

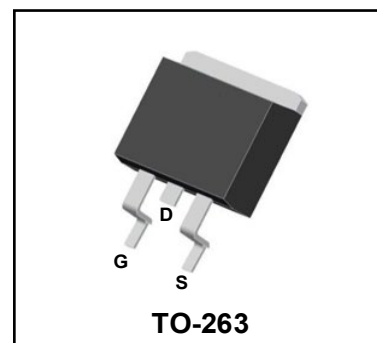
WMM053NV8HGS uses Wayon's advanced power trench MOSFET technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance. This device is well suited for high efficiency fast switching applications.

## Features

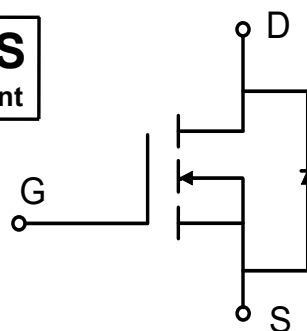
- $V_{DS} = 85V$ ,  $I_D = 125A$   
 $R_{DS(on)} < 5.5m\Omega$  @  $V_{GS} = 10V$
- High Speed Power Switching
- Low Gate Charge
- Low  $R_{DS(ON)}$
- 100% EAS Guaranteed

## Applications

- Battery Management System
- Power Management Switching
- Motor Drive



**RoHS**  
compliant

Absolute Maximum Ratings ( $T_c = 25^\circ C$ , unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	85	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$T_C = 25^\circ C$	$I_D$	125	A
	$T_C = 100^\circ C$		79	
Pulsed Drain Current <sup>4</sup>		$I_{DM}$	500	A
Single Pulse Avalanche Energy <sup>3</sup>		EAS	204.8	mJ
Total Power Dissipation <sup>4</sup>	$T_C = 25^\circ C$	$P_D$	162	W
Operating Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 to 150	$^\circ C$

## Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	$R_{\theta JA}$	58	$^\circ C/W$
Thermal Resistance from Junction-to-Lead	$R_{\theta JC}$	0.77	$^\circ C/W$

## Electrical Characteristics (Tc = 25°C, unless otherwise noted)

Parameter		Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics							
Drain-Source Breakdown Voltage		$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	85	-	-	V
Gate-body Leakage current		$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current	$T_J = 25^{\circ}C$	$I_{DSS}$	$V_{DS} = 80V, V_{GS} = 0V$	-	-	1	$\mu A$
	$T_J = 100^{\circ}C$			-	-	100	
Gate-Threshold Voltage		$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	3	4	V
Drain-Source on-Resistance <sup>2</sup>		$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20A$	-	4.6	5.5	m $\Omega$
Forward Transconductance <sup>2</sup>		$g_{fs}$	$V_{DS} = 5V, I_D = 20A$	-	55	-	S
Dynamic Characteristics							
Input Capacitance		$C_{iss}$	$V_{DS} = 40V, V_{GS} = 0V, f = 1MHz$	-	4645	-	pF
Output Capacitance		$C_{oss}$		-	673	-	
Reverse Transfer Capacitance		$C_{rss}$		-	41	-	
Switching Characteristics							
Gate Resistance		$R_g$	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	-	1.8	-	$\Omega$
Total Gate Charge		$Q_g$	$V_{GS} = 10V, V_{DS} = 40V, I_D = 50A$	-	61.3	-	nC
Gate-Source Charge		$Q_{gs}$		-	21	-	
Gate-Drain Charge		$Q_{gd}$		-	11	-	
Turn-on Delay Time		$t_{d(on)}$	$V_{GS} = 10V, V_{DS} = 40V, R_G = 3\Omega, I_D = 50A$	-	16.5	-	ns
Rise Time		$t_r$		-	51.8	-	
Turn-off Delay Time		$t_{d(off)}$		-	37.1	-	
Fall Time		$t_f$		-	8.2	-	
Drain-Source Body Diode Characteristics							
Diode Forward Voltage <sup>2</sup>		$V_{SD}$	$I_S = 50A, V_{GS} = 0V$	-	-	1.2	V
Continuous Source Current <sup>1,5</sup>		$I_S$	$V_G = V_D = 0V, \text{ Force Current}$	-	-	125	A
Reverse Recovery Time <sup>2</sup>		$t_{rr}$	$I_F = 20A, di/dt = 100A/\mu S$	-	69	-	ns
Reverse Recovery Charge <sup>2</sup>		$Q_{rr}$		-	141	-	nC

## Notes:

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is  $V_{DD}=35V, V_{GS}=10V, L=0.4mH, I_{AS}=32A$
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

## Typical Characteristics

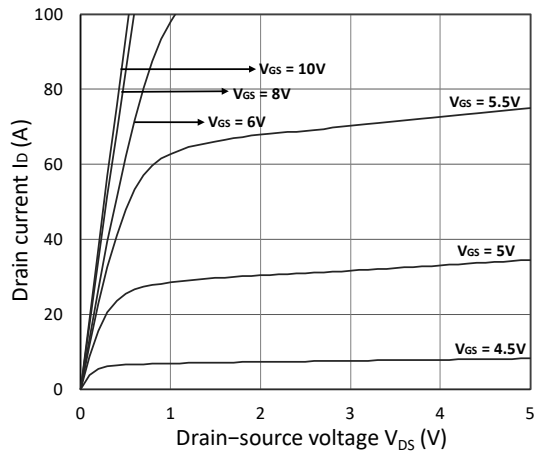


Figure 1. Output Characteristics

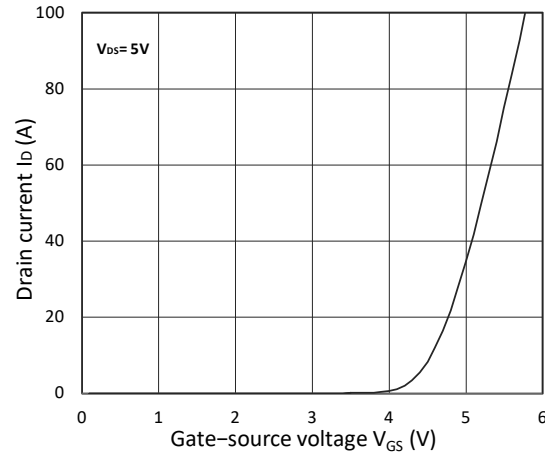


Figure 2. Transfer Characteristics

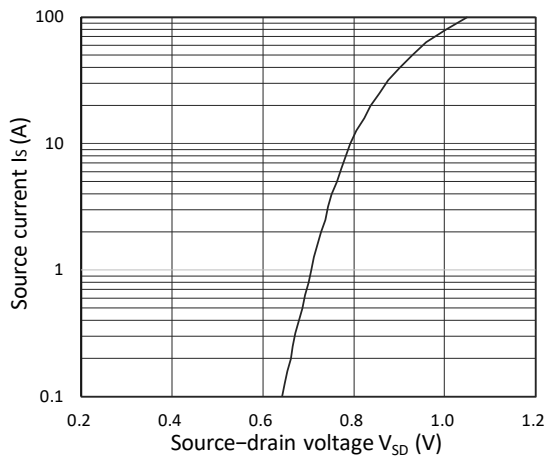
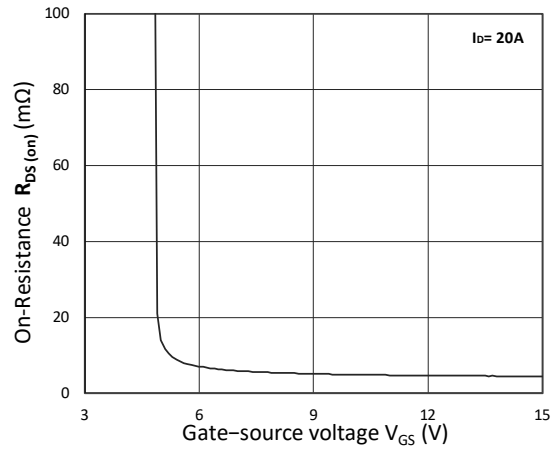
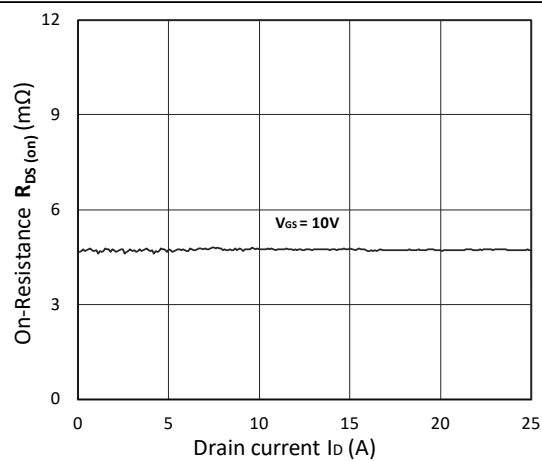
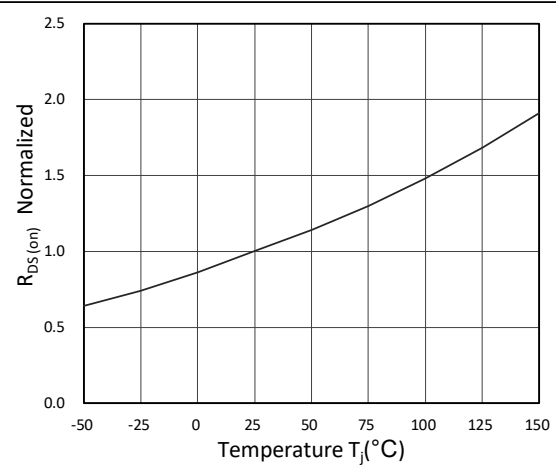


Figure 3. Forward Characteristics of Reverse

Figure 4.  $R_{DS(on)}$  vs.  $V_{GS}$ Figure 5.  $R_{DS(on)}$  vs.  $I_D$ Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

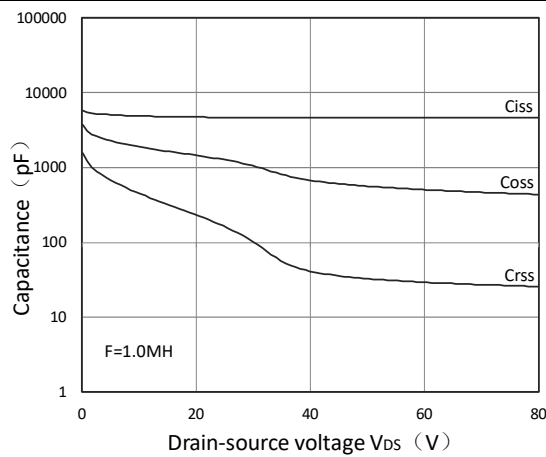


Figure 7. Capacitance Characteristics

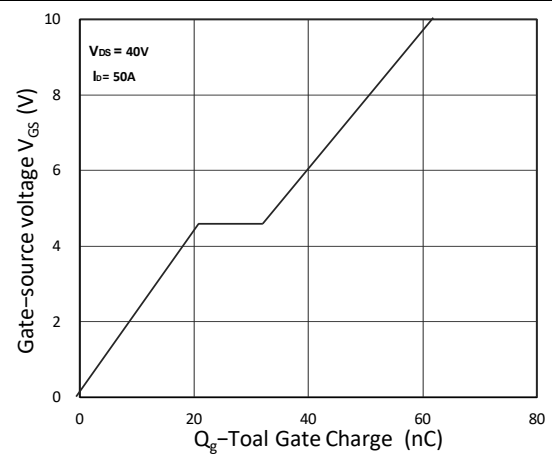


Figure 8. Gate Charge Characteristics

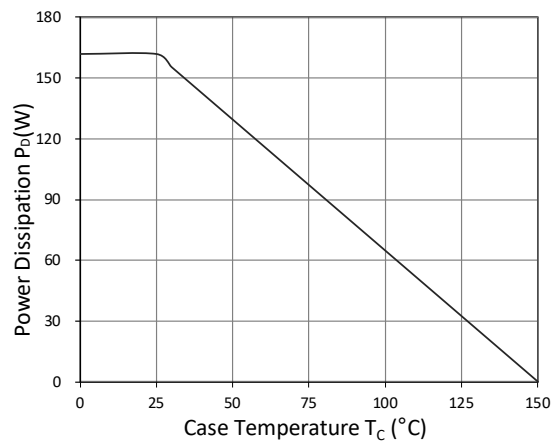


Figure 9. Power Dissipation

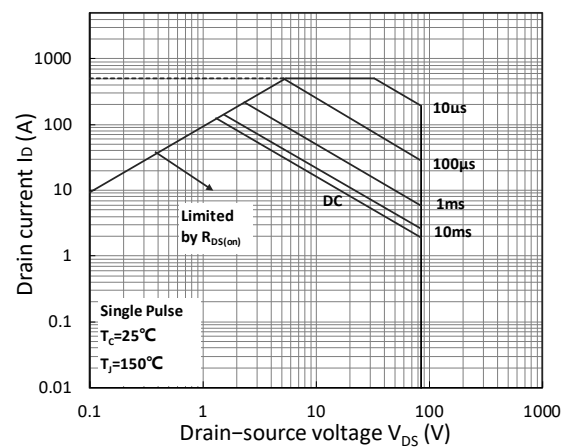


Figure 10. Safe Operating Area

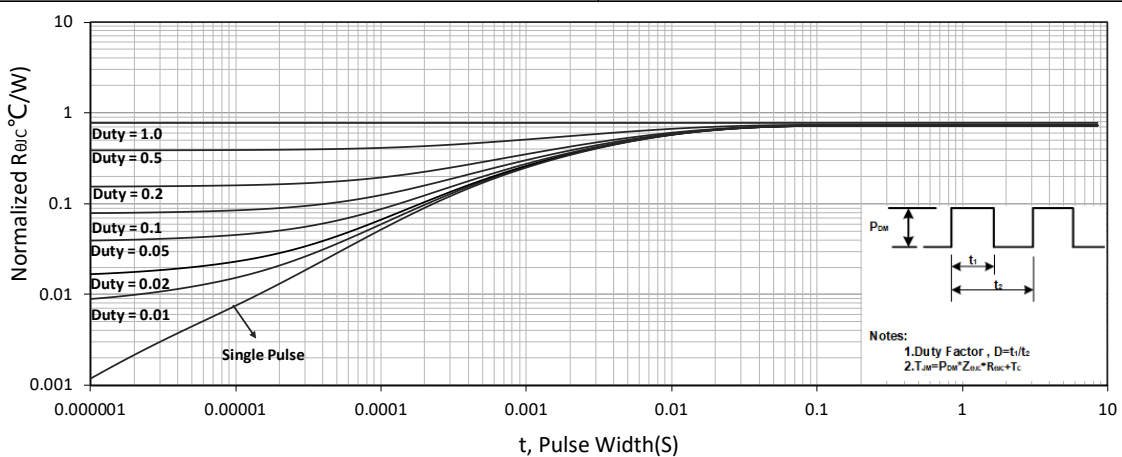


Figure 11. Normalized Maximum Transient Thermal Impedance

## Test Circuit

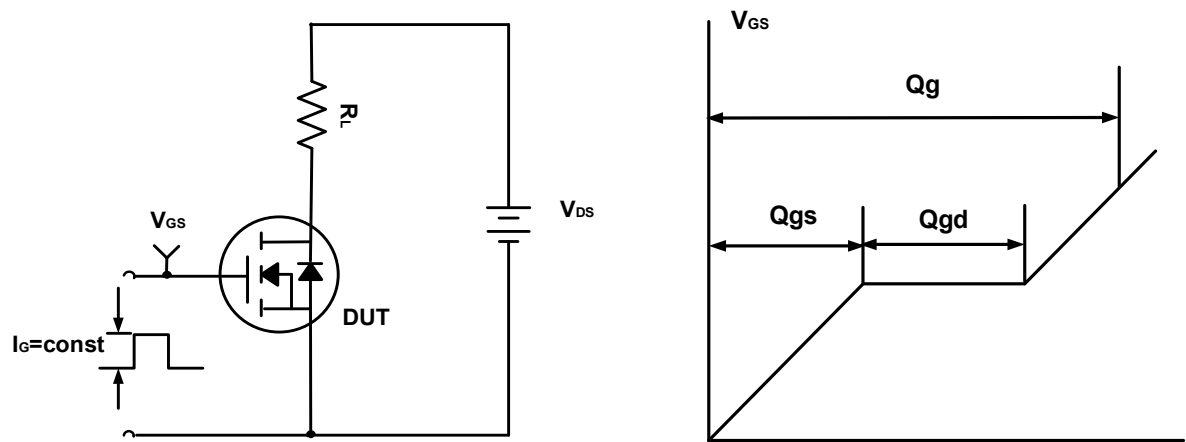


Figure A. Gate Charge Test Circuit &amp; Waveforms

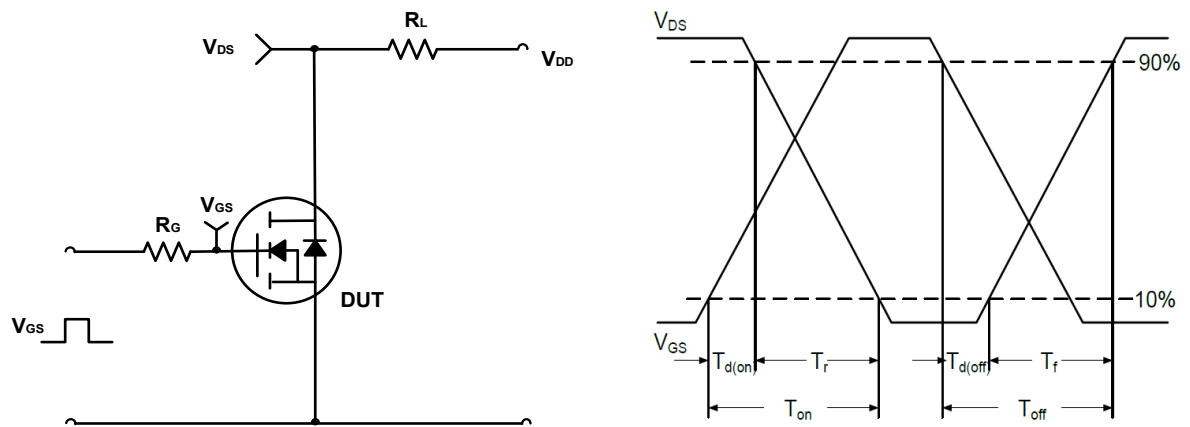


Figure B. Switching Test Circuit &amp; Waveforms

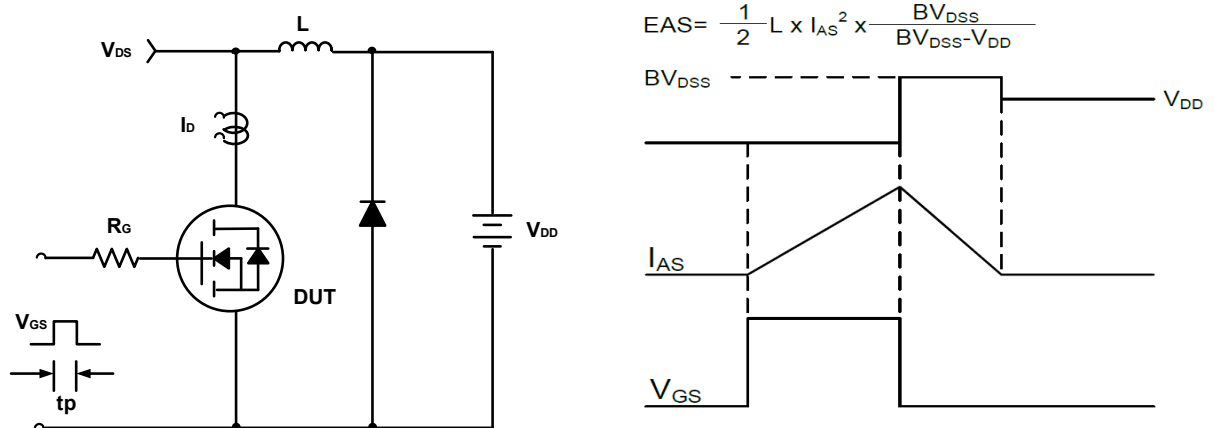
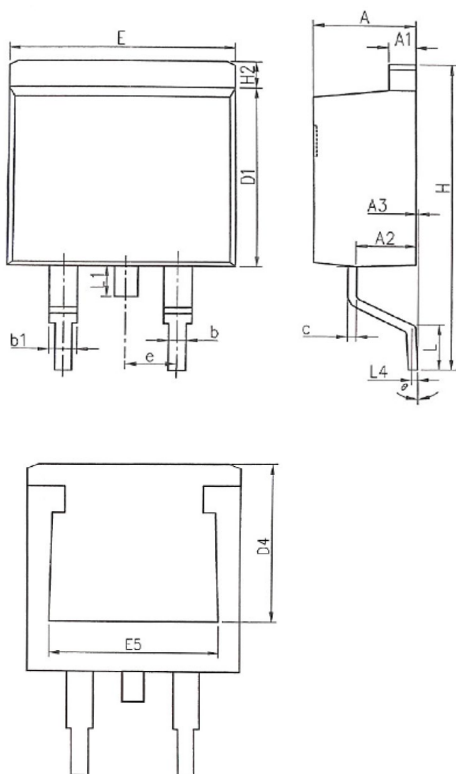


Figure C. Unclamped Inductive Switching Circuit &amp; Waveforms

## Mechanical Dimensions for TO-263

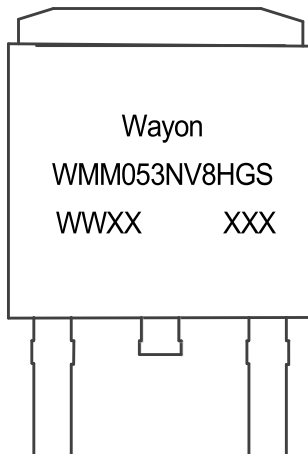
## COMMON DIMENSIONS



SYMBOL	MM	
	MIN	MAX
A	4.37	4.89
A1	1.17	1.42
A2	2.20	2.90
A3	0.00	0.25
b	0.70	0.96
b1	1.17	1.47
c	0.28	0.60
D1	8.45	9.30
D4	6.60	-
E	9.80	10.40
E5	7.06	-
e	2.54BSC	
H	14.70	15.70
H2	1.07	1.47
L	2.00	2.80
L1	-	1.75
L4	0.254BSC	
$\theta$	0°	9°

**Ordering Information**

Part	Package	Marking	Packing method
WMM053NV8HGS	TO-263	WMM053NV8HGS	Tape and Reel

**Marking Information**

WMM053NV8HGS = Device code

WWXX XXX= Date code

**Contact Information**

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